

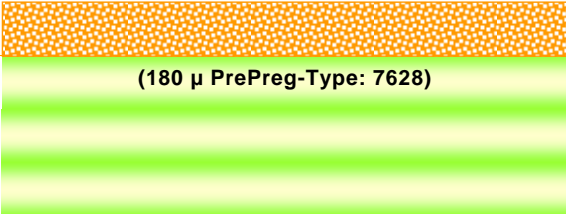
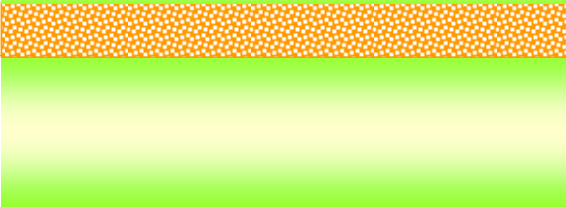
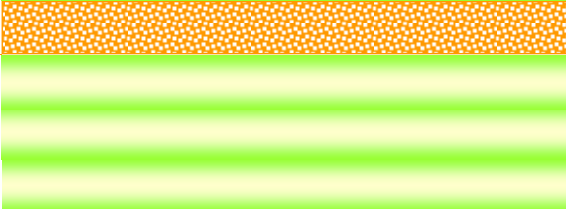

Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

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columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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| Layers | in μ | Material | Build-Up | Assembly | |
|-----------------|-----------|----------|--|----------|---|
| Layer-1 | 105 μ | Copper |  | A1 | |
| | 180 μ | Prepreg | | | |
| | 180 μ | Prepreg | | | |
| | 180 μ | Prepreg | | | |
| Layer-2 | 105 μ | Copper |  | | B |
| | 360 μ | L-FR4 | | | |
| Layer-3 | 105 μ | Copper |  | | |
| | 180 μ | Prepreg | | | |
| | 180 μ | Prepreg | | | |
| | 180 μ | Prepreg | | | |
| Layer-99 | 105 μ | Copper |  | | |

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